

Product Description

Shin-Etsu's KE-1891 is a UL 94 V-0 rated, single component, heat cure, thixotropic adhesive that will cure to form a tough, durable elastomer. KE-1891 exhibits superior thermal conductivity and excellent, unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- Superior thermal conductivity
- UL 94 V-0 certified
- Single component
- Heat cure
- Thixotropic paste

Typical Applications

- Form-in-place gasketing
- Sealing electronics

Typical Properties

Type	Adhesive/Sealant
Cure Type	Addition
One/Two Component	One
UL	Y
Cold Storage	Y
Low Molecular Weight Siloxane Stripped?	Y
Color	Gray
Density @ 23C (g/cm ³)	3.06
Cure Conditions	1hr @ 120C
Shore A Hardness	96
Tensile Strength (MPa)	4.80
% Elongation	10
Shear Strength (MPa)	0.80
Volume Resistivity (TΩ·m)	3.4
Dielectric Strength (kV/mm)	25
Thermal Conductivity (W/m·K)	4.00
Usable Temperature Range (C)	-40 to +180

Note: Values are not for specification purposes.

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